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# 5x7mm Precision TCXO In Stock at Digi-Key

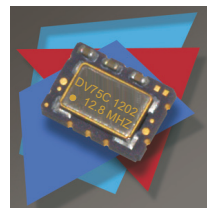


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## Description:

The Connor-Winfield's DV75C is a 5x7mm Surface Mount Temperature Compensated Crystal Controlled Oscillator (TCXO) with LVCMOS output. Through the use of Analog Temperature Compensation the DV75C is capable of holding sub 1-ppm stabilities over the -40 to 85°C temperature range. The DV75C meets STRATUM 3 requirements.



## Features:

**Model: DV75C**  
3.3 Vdc Operation  
LVCMOS Output  
Frequency Stability:  $\pm 0.28$  ppm  
Temperature Range: -40 to 85°C  
Low Jitter <1ps RMS  
5x7mm Surface Mount Package  
Tape and Reel Packaging  
RoHS Compliant / Pb Free

## Applications:

- IEEE 1588 Applications
- Synchronous Ethernet slave clocks, ITU-T G.8262 EEC options 1 & 2
- Compliant to Stratum 3, GR-1244-CORE, GR-253-CORE & ITU-T-G.812 Type IV
- Wireless Communications
- Small Cells
- Test and Measurement

### Absolute Maximum Ratings

Parameter	Absolute Maximum Ratings			Units	Notes
	Minimum	Nominal	Maximum		
Storage Temperature	-55	-	85	°C	
Supply Voltage (Vcc)	-0.5	-	6.0	Vdc	
Input Voltage	-0.5	-	Vcc+0.5	Vdc	

### Operating Specifications

Parameter	Operating Specifications			Units	Notes
	Minimum	Nominal	Maximum		
Nominal Frequency (Fo)	-	10.0, 12.8 or 20.0	-	MHz	
Frequency Calibration @ 25 °C	-1.0	-	1.0	ppm	1
Frequency Stability vs. Temperature	-0.28	-	0.28	ppm	2
Holdover Stability (Over 24 Hours)	-0.32	-	0.32	ppm	3
Frequency vs. Load Stability	-0.20	-	0.20	ppm	$\pm 5\%$
Frequency vs. Voltage Stability	-0.20	-	0.20	ppm	$\pm 5\%$
Static Temperature Hysteresis	-	-	0.4	ppm	Absolute, 4
Total Frequency Tolerance:	-4.6	-	4.6	ppm	5
Operating Temperature Range:	-40	-	85	°C	
Supply Voltage (Vcc)	3.135	3.3	3.465	Vdc	$\pm 5\%$
Supply Current (Icc)	-	-	6	mA	
Period Jitter	-	3	5	ps rms	
Integrated Phase Jitter	-	0.5	1.0	ps rms	6
Typical Phase Noise Fo = 10.0 MHz					
SSB Phase Noise at 10Hz offset	-	-80	-	dBc/Hz	
SSB Phase Noise at 100Hz offset	-	-110	-	dBc/Hz	
SSB Phase Noise at 1KHz offset	-	-135	-	dBc/Hz	
SSB Phase Noise at 10KHz offset	-	-150	-	dBc/Hz	
SSB Phase Noise at 100KHz offset	-	-150	-	dBc/Hz	
Start-up Time	-	-	5	ms	

### LVCMOS Output Characteristics

Parameter	LVCMOS Output Characteristics			Units	Notes
	Minimum	Nominal	Maximum		
Load	-	15	-	pF	7
Voltage (High) (Voh)	90%Vcc	-	-	Vdc	
(Low) (Vol)	-	-	10%Vcc	Vdc	
Duty Cycle at 50% of Vcc	45	50	55	%	
Rise / Fall Time 10% to 90%	-	-	8	ns	

### Package Characteristics

Package: Hermetically sealed crystal mounted on a ceramic package

### Environmental Characteristics

Vibration: Vibration per Mil Std 883E Method 2007.3 Test Condition A  
Shock: Mechanical Shock per Mil Std 883E Method 2002.4 Test Condition B.  
Soldering Process: RoHS compliant lead free. See soldering profile on page 2.

### Ordering Information

DV75C-010.0M\*, DV75C-012.8M\* or DV75C-020.0M\*

\* For the tape and reel option, add -T to the end of the part number. Example: DV75C-010.0M-T



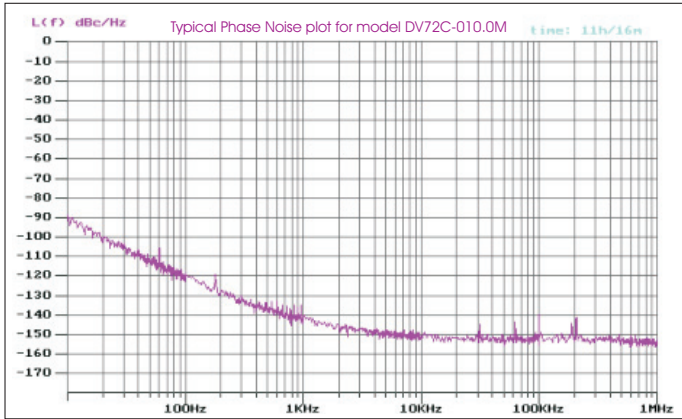
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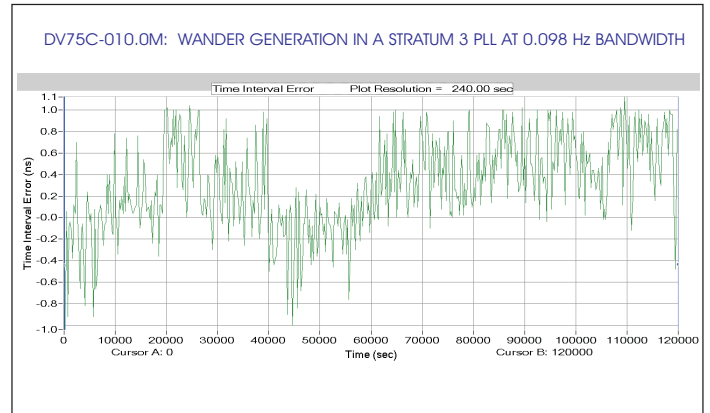


- Notes:**
1. Initial calibration @ 25°C. Specifications at time of shipment after 48 hours of operation.
  2. Frequency stability vs. change in temperature.  $[\pm(F_{max} - F_{min})/(2 \cdot F_0)]$ .
  3. Inclusive of frequency stability, supply voltage change ( $\pm 1\%$ ), load change, aging, for 24 hours.
  4. Frequency change after reciprocal temperature ramped over the operating range. Frequency measured before and after at 25°C.
  5. Inclusive of calibration @ 25°C, frequency vs. change in temperature, change in supply voltage ( $\pm 5\%$ ), load change ( $\pm 5\%$ ), reflow soldering process and 20 years aging, referenced to  $F_0$
  6. BW = 12 KHz to 20 MHz.
  7. For best performance it is recommended that the circuit connected to this output should have an equivalent input capacitance of 15pF.

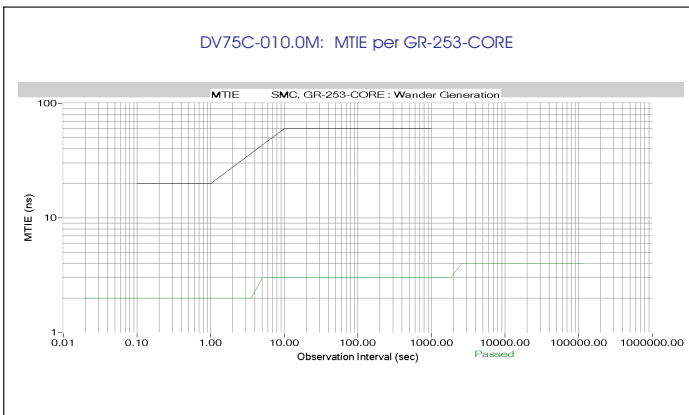
## Phase Noise Information



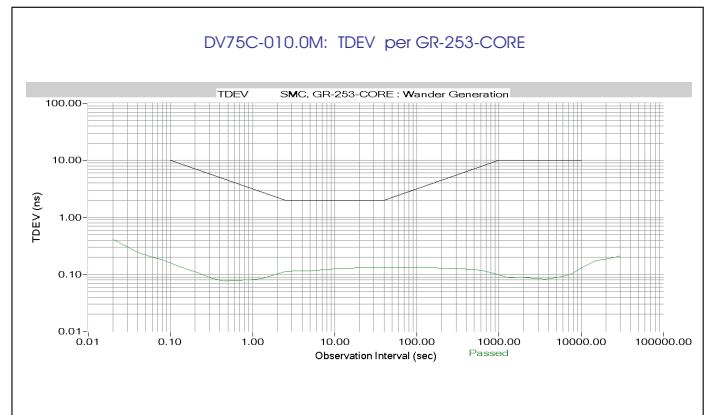
## TIE



## MTIE

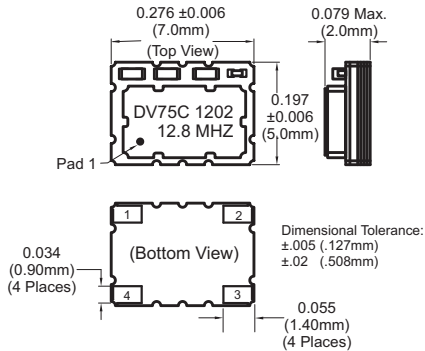


## TDEV

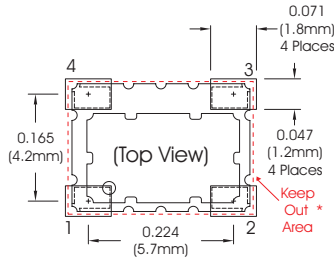




## Package Layout



## Suggested Pad Layout

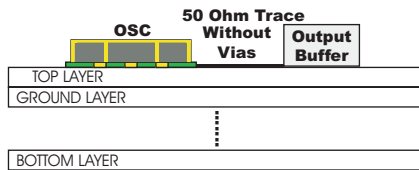
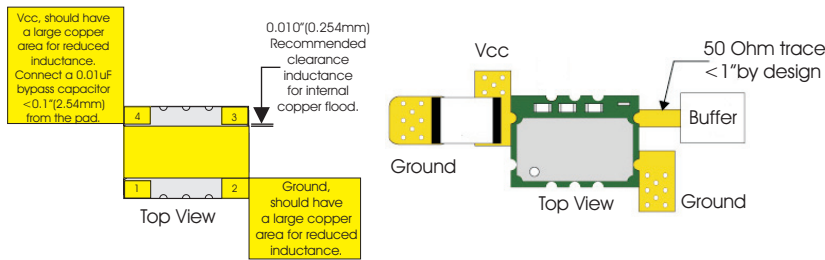


\* Do not route any traces in the keep out area. It is recommended the next layer under the keep out area is to be ground plane.

## Pad Connections

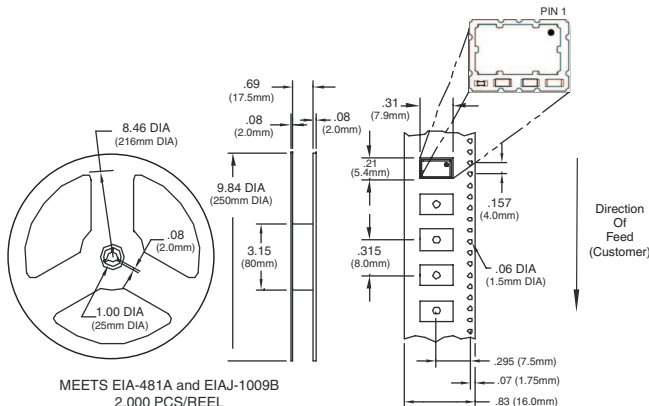
1:	N/C
2:	Ground
3:	Output (Fo)
4:	Supply Voltage (Vcc)

## Design Recommendations

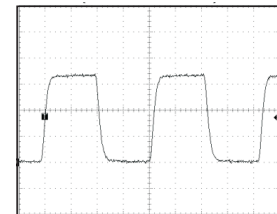


Attention: To achieve optimal frequency stability, and in some cases to meet the specification stated on this data sheet, it is required that the circuit connected to this TCXO output must have the equivalent input capacitance that is specified by the nominal load capacitance. Deviations from the nominal load capacitance will have a graduated effect on the stability of approximately 20 ppb per pF load difference.

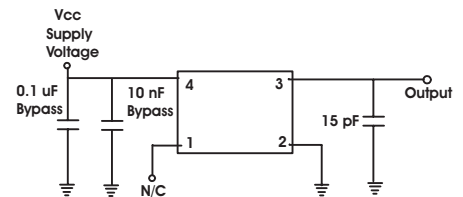
## Tape and Reel Dimensions



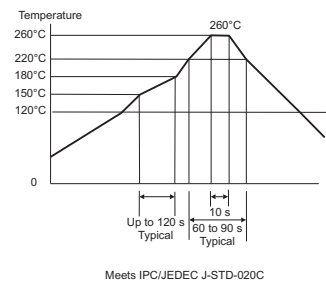
## Output Waveform



## Test Circuit



## Solder Profile



## Revision History

Revision 00	Data sheet released 01/11/12
Revision 01	Removed tri-state information from features and description. 11/26/12.
Revision 02	Added "Applications", Phase noise, TIE, MTIE and TDEV plots. 04/15/13.

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